

Engineering Bill of Materials



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Project Name:	PMP10703
Project File:	PMP10703_LM2733 flyback.PrjPcb
Base ID:	
PCB Rev:	PMP10703_LM2733 flyback.PcbDoc
Schematic Rev:	PMP10703_LM2733 flyback.SchDoc
Assembly Variant:	None
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Item	Designator	Description	RoHS	Manufacturer	PartNumber	Quantity	Library Name
1	C1, C6, C8	CAP, CERM, 10 礮, 25 V, +/- 10%, X7R, 1206	Y	MuRata	GRM31CR71E106KA12L	3	Capacitor_Ceramic.IntLib
2	C3	CAP, CERM, 1 礮, 25 V, +/- 10%, X5R, 0603	Y	MuRata	GRM188R61E105KA12D	1	Capacitor_Ceramic.IntLib
3	C4	CAP, CERM, DNP 16V, +/-10%, X7R, 0603	Y	TDK	C1608X7R1C105K	1	Capacitor_Ceramic.IntLib
4	C5	CAP, CERM, 10 礮, 25 V, +/- 20%, X5R, 0805	Y	MuRata	GRM219R61E106MA12	1	Capacitor_Ceramic.IntLib
5	C9	CAP, CERM, 390 pF, 50 V, +/- 1%, COG/NP0, 0603	Y	Kemet	C0603C391F5GACTU	1	Capacitor_Ceramic.IntLib
6	C10	CAP, CERM, 1000pF, 250V, +/-5%, COG/NP0, 0805	Y	TDK	C2012C0G2E102J	1	Capacitor_Ceramic.IntLib
7	D1	Diode, Schottky, 30 V, 0.1 A, SOD-323	Y	Diodes Inc.	SD107WS-7-F	1	Diode.IntLib
8	D2, D3	Diode, Schottky, 40 V, 0.35 A, SOD-123	Y	Diodes Inc.	SD103AW-7-F	2	Diode.IntLib
9	R1	RES, 43.2 k, 1%, 0.1 W, 0603	Y	Yageo America	RC0603FR-0743K2L	1	Resistor_0603.IntLib
10	R3	RES, DNP, 0.1%, 0.1 W, 0603	Y	Yageo America	RT0603BRD0775K9L	1	Resistor_0603.IntLib
11	R4, R6	RES, 140 k, 0.5%, 0.1 W, 0603, RES, 10 k, 0.5%, 0.1 W, 0603	Y	Yageo America	RT0603DRE07140KL	2	Resistor_0603.IntLib
12	R5	RES, 12 k, 5%, 0.1 W, 0603	Y	Vishay-Dale	CRCW060312K0JNEA	1	Resistor_0603.IntLib
13	T1	Transformer, 2.5 uH, SMT	Y	Würth Elektronik	750311880	1	Inductor_Wurth.SchLib
14	TP1, TP2, TP3, TP4, TP5	PCB Pin, TH	Y	Mill-Max	3125-2-00-34-00-00-08-0	5	Connectors.IntLib
15	U1	0.6/1.6 MHz Boost Converters With 40V Internal FET Switch, 5-pin SOT-23	N	Texas Instruments	LM2733YMF	1	NSC Switcher.IntLib

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